**PCB description：PE-H02-S2001-2-3 V2.0 1118**

**1. General information:**

1) 4 layers PCB

2) PCB material: RF4

3) COLOUR: blue

3) Copper thickness inner layer 2oz, outer layer 3oz

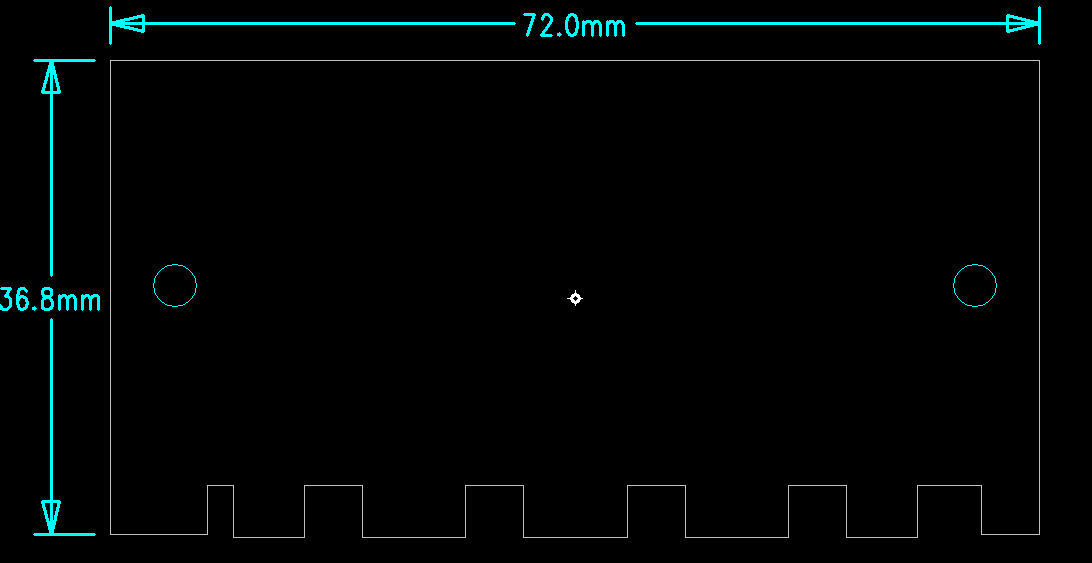
4) Thickness 2mm (+-10%)

5) Silkscreen includes component border, 2D line, no reference

7) Resin plug vias

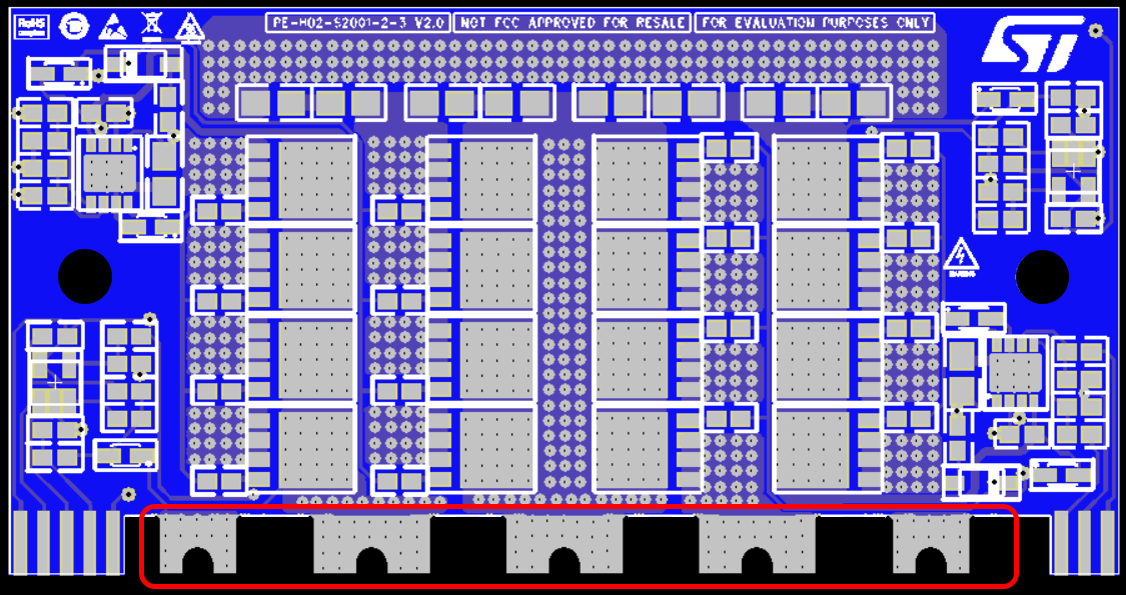
8) Chemical gold (vias and solder mask)

9) 2 screw holes, position in the 24th drill drawing layer, the position is as below:



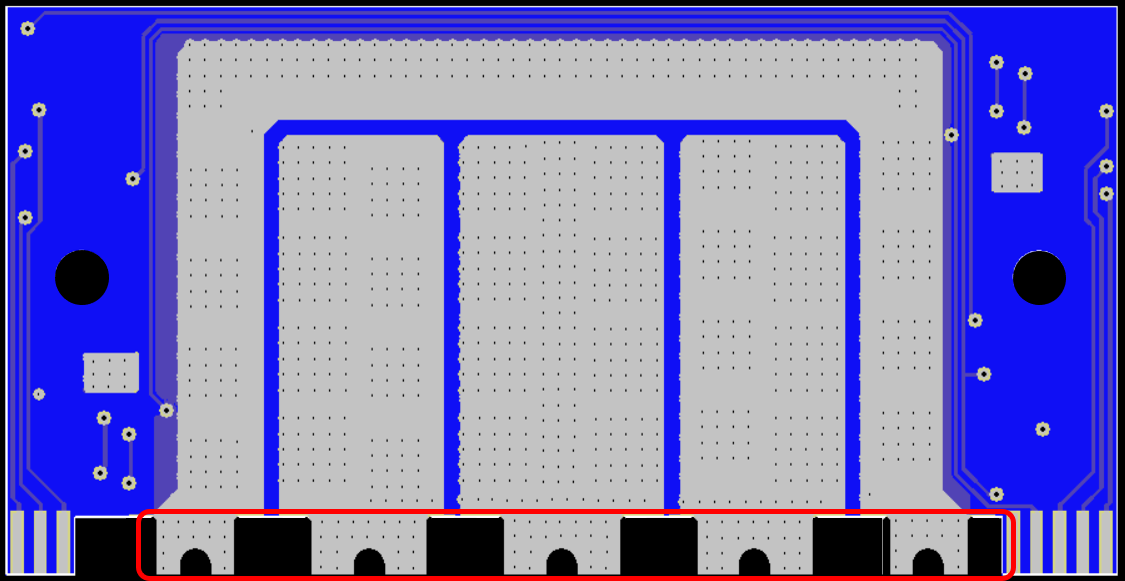
**2. Top View:**

The part circled in red is the terminal for connecting to the motherboard, with copper foil on the side



**3. Bottom view:**

The part circled in red is the terminal for connecting to the motherboard, with copper foil on the side



**4. Details:**

|  |  |  |  |  |  |  |  |  |  |
| --- | --- | --- | --- | --- | --- | --- | --- | --- | --- |
| SUPPORT TYPE | | | | |  | FR4 Standard | | | |
| Nr. LAYERS | | | | |  | 4 | | | |
| COPPER EXTERNAL THICKNESS | | | | |  | See stack-up | | | |
| COPPER INTERNAL THICKNESS | | | | |  | See stack-up | | | |
| Vias Metallized | | | | |  | YES | | | |
| BOARD size(mm): | | | | |  | 72x36.8 | | | |
| SERIGRAFY TOP | | | | |  | YES | | | |
| SERIGRAFY BOT | | | | |  | NOT | | | |
| SOLDER MASK TOP | | | | |  | YES | | | |
| SOLDER MASK Bottom | | | | |  | YES | | | |
| SOLDER MASK COLOR | | | | |  | BLU | | | |
| SOLDER PASTE TOP (required if SMD used) | | | | |  | YES | | | |
| SOLDER PASTE Bottom (required if SMD used) | | | | |  | NOT | | | |
| PCB-Precision Class- | | |  |  |  |  | | | |
| Class-4 Track width-12mils- hole min.28mils | | | | |  | / | | | |
| Class-5 Track width-8mils- hole min.20mils | | | | |  | / | | | |
| Class-6 Track width-6mils- hole min.16mils | | | | |  | YES | | | |
| CROP inside Gerber files | | | | |  | YES | | | |
| Final Finishes | | |  |  |  |  | | | |
| Hot Air Levelling (HAL) | | | | |  | / | | | |
| Hot Air Levelling Lead Free (HAL lead free) | | | | |  | YES | | | |
| CHEMICAL GOLD | | | | |  | YES | | | |
| CHEMICAL TIN | | | | |  | / | | | |
| ELECTROLITIC GOLD | | | | |  | / | | | |
| COPPER PASSIVATED | | | | |  | / | | | |
| CHEMICAL TIN | | | | |  | / | | | |
|  |  |  |  |  |  |  |  |  |  |
| CLASS OF ACCURACY -SIZE & INFORMATION | | | | | |  |  |  |  |
|  |  |  |  |  |  |  |  |  |  |
| **Class of accuracy** | | | **4** | **5** | **6** |  |  |  |  |
| Route width [mil (mm)] | | | 12 (0.3048) | 8 (0.2032) | 6 (0.1524) |  |  |  |  |
| Isolation width [mil (mm)] | | | 12 (0.3048) | 8 (0.2032) | 6 (0.1524) |  |  |  |  |
| Drill diameter (ØD) [mil (mm)] | | | 28 (0.7112) | 20 (0.5080) | 16 (0.4064) |  |  |  |  |
| Pad diameter (ØPAD) [mil] | | | ØD + 24 | ØD + 16 | ØD + 12 |  |  |  |  |
| Solder mask diameter [mil] | | | ØPAD + 10 | ØPAD + 8 | ØPAD + 6 |  |  |  |  |

**Note：**Attached is the original PCB file, please ask the PCB manufacturer to help check whether there is any error in the Gerber file, if there is any error, you can re-export the Gerber file according to above specification.